

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF THE CLAIMS:

1. (Currently amended) A capacitor, comprising:
  - a fixed charge plate disposed ~~in~~ on a semiconductor substrate;
  - a fixed actuator plate disposed upon the semiconductor substrate;
  - a moveable charge plate disposed above the fixed charge plate; and
  - a stiffener disposed on a center portion of the moveable charge plate.
2. (Original) The capacitor according to claim 1, the movable charge plate further comprising:
  - a first separation distance between the fixed charge plate and the stiffener,wherein the first separation distance is constant.
3. (Original) The capacitor according to claim 1, further comprising:
  - a first separation distance between the fixed charge plate and the stiffener,wherein the first separation distance is constant; and
  - a second separation distance between the fixed charge plate and portions of the movable charge plate, wherein the second separation distance is variable.
4. (Original) The capacitor according to claim 1, wherein the fixed charge plate has a first surface area and the movable charge plate has a second surface area that is smaller than the first surface area.
5. (Original) The capacitor according to claim 1, wherein the movable charge plate comprises a solid surface plate and a broken surface suspension.

6. (Original) The capacitor according to claim 1, wherein the movable charge plate comprises a solid surface plate and a broken surface suspension, and wherein the broken surface suspension has an undulating configuration.
7. (Original) The capacitor according to claim 1, wherein the fixed charge plate has a first surface area and the movable charge plate has a second surface area that is smaller than the first surface area, and wherein the movable charge plate comprises a solid surface plate and a broken surface suspension.
8. (Original) The capacitor according to claim 1, wherein the fixed charge plate has a first surface area and the movable charge plate has a second surface area that is smaller than the first surface area, wherein the movable charge plate comprises a solid surface plate and a broken surface suspension, and wherein the broken surface suspension has an undulating configuration.
9. (Currently amended) A variable capacitor in a semiconductor device comprising:  
a movable charge plate disposed in a semiconductor substrate, comprising a flexible section;  
a fixed actuator plate disposed on the substrate, wherein the fixed actuator plate is capable of moving the moveable charge plate; and  
a stiffener disposed on a center portion of the movable charge plate.
10. (Previously presented) The variable capacitor in a semiconductor device according to claim 9, wherein the movable charge plate further comprises a flexible dielectric layer capable of suspending the moveable charge plate.

11. (Previously presented) The variable capacitor in a semiconductor device according to claim 9, wherein the flexible section is capable of suspending the movable charge plate.
12. (Cancelled)
13. (Previously presented) The variable capacitor in a semiconductor device according to claim 9, further comprising a moveable actuator plate capable of moving the moveable charge plate.
14. (Currently amended) A capacitor comprising:
  - a first fixed charge plate disposed ~~in~~ on a semiconductor substrate;
  - a fixed actuator plate disposed upon the semiconductor substrate;
  - a flexible dielectric disposed above the first fixed charge plate;
  - a second charge plate disposed upon the flexible dielectric, wherein the flexible dielectric is interposed between the first fixed charge plate and the second charge plate; and
  - a stiffener disposed upon a center portion of the second charge plate.
15. (Cancelled)
16. (Original) The capacitor according to claim 14, further comprising:
  - a stiffener affixed to the second charge plate, wherein the second charge plate is interposed between the stiffener and the flexible dielectric structure.
17. (Previously presented) A microelectromechanical structure variable capacitor comprising:

a fixed charge plate disposed upon an elevated semiconductor substrate;  
a fixed actuator plate disposed upon a lower semiconductor substrate,  
wherein the fixed actuator plate is below the fixed charge plate;  
a moveable charge plate suspended above the fixed charge plate; and  
a stiffener disposed upon a center portion of the moveable charge plate.

18. (Original) The microelectromechanical structure variable capacitor according to claim 17, wherein the fixed charge plate has a first surface area and the movable charge plate has a second surface area that is larger than the fixed charge plate.

19. (Original) The microelectromechanical structure variable capacitor according to claim 17, wherein the movable charge plate comprises a solid surface plate and a broken surface suspension.

20. (Original) The microelectromechanical structure variable capacitor according to claim 17, further comprising:

a movable actuator plate disposed over the fixed actuator plate.

21. (Original) The microelectromechanical structure variable capacitor according to claim 17, wherein the elevated substrate and the lower substrate have a negligible elevational difference.